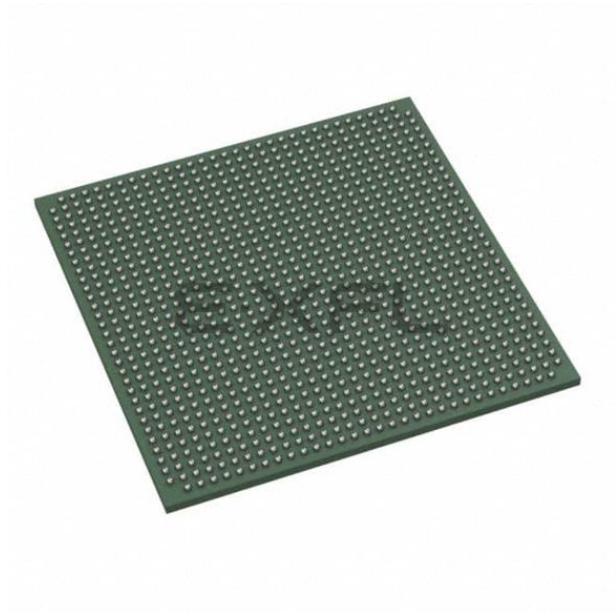
Lattice Semiconductor Corporation - LFSCM3GA25EP1-7FFN1020C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	6250
Number of Logic Elements/Cells	25000
Total RAM Bits	1966080
Number of I/O	476
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFCBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga25ep1-7ffn1020c

toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-9 illustrates the DCS Block diagram.

Figure 2-9. DCS Block Diagram

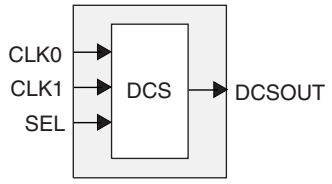
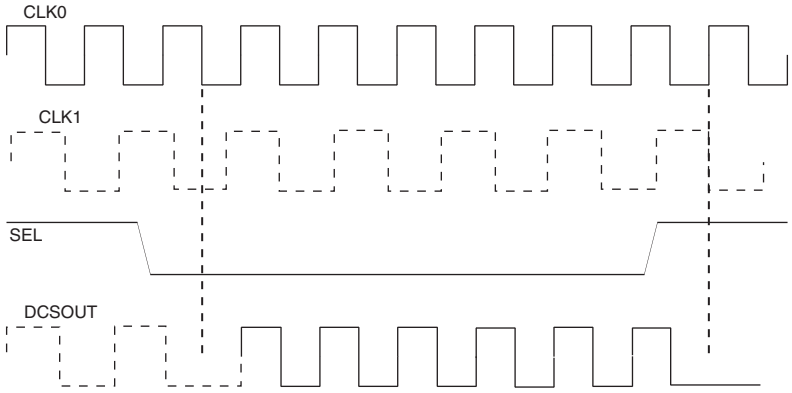


Figure 2-10 shows timing waveforms for one of the DCS operating modes. The DCS block can be programmed to other modes. For more information on the DCS, please see details of additional technical documentation at the end of this data sheet.

Figure 2-10. DCS Waveforms



Clock Boosting

There are programmable delays available in the clock signal paths in the PFU, PIC and EBR blocks. These allow setup and clock-to-output times to be traded to meet critical timing without slowing the system clock. If this feature is enabled then the design tool automatically uses these delays to improve timing performance.

Global Set/Reset

There is a global set/reset (GSR) network on the device that is distributed to all FFs, PLLs, DLLs and other blocks on the device. This GSR network can operate in two modes:

a) asynchronous - no clock is required to get into or out of the reset state.

b) synchronous - The global GSR net is synchronized to a user selected clock. In this mode it continues to be asynchronous to get into the reset state, but is synchronous to get out of the reset state. This allows all registers on the device to become operational in the same clock period. The synchronous GSR goes out of reset in two cycles from the clock edge where the setup time of the FF was met (not from the GSR being released).

sysCLOCK Phase Locked Loops (PLLs)

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider and two clock output dividers. The input divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal.

3. **Bottom Side (Banks 4 and 5)**
   These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but true HLVDS and RSDS differential drivers are not available. Adaptive input logic is available on PIOs A or C.

Table 2-8 lists the standards supported by each side.

Table 2-8. I/O Standards Supported by Different Banks

Description	Top Side Banks 1	Right Side Banks 2-3	Bottom Side Banks 4-5	Left Side Banks 6-7
I/O Buffer Type	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver
Output Standards Supported	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]
Input Standards Supported	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Clock Inputs	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Differential Output Support via Emulation	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL
AIL Support	No	Yes	Yes	Yes

1. Input only.
2. Input only. Outputs supported by bussing multiple outputs together.

Supported Standards

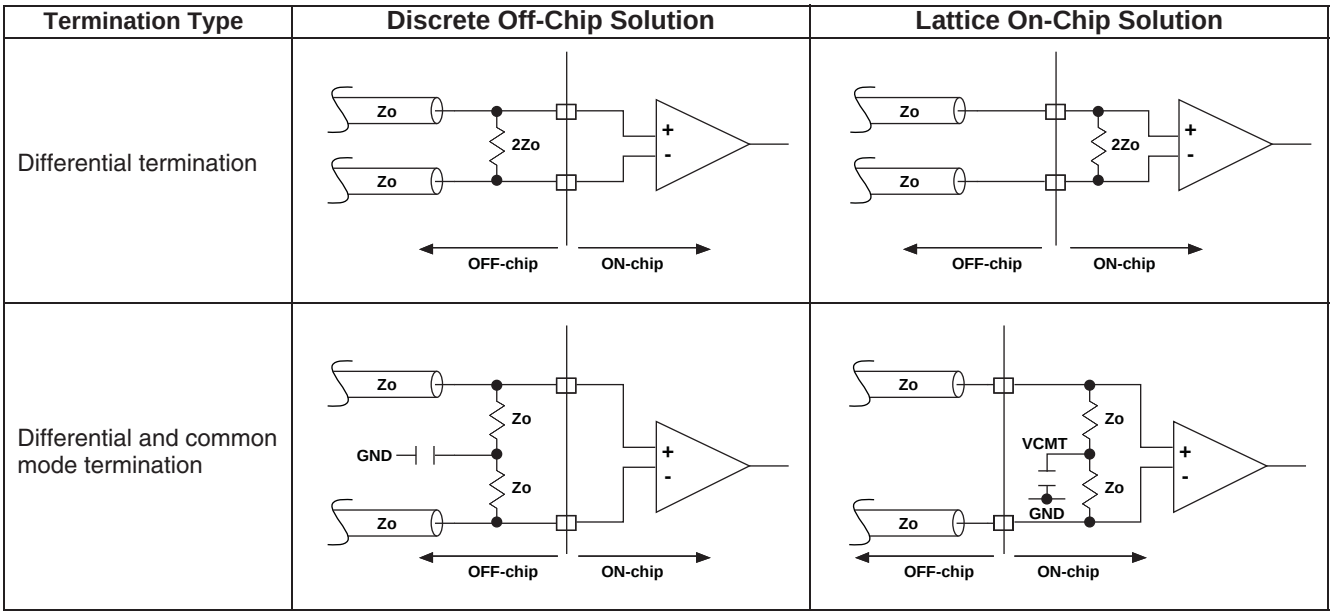
The LatticeSC PURESPEED I/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 12, 15, 18, 25 and 33 standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, termination resistance, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL, HSTL, GTL (input only), GTL+ (input only), PCI33, PCIX33, PCIX15, AGP-1X33 and AGP-2X33. Differential standards supported include LVDS, RSDS, BLVDS, MLVDS, LVPECL, differential SSTL and differential HSTL. Tables 12 and 13 show the I/O standards (together with their supply and reference voltages) supported by the LatticeSC devices. The tables also provide the available internal termination schemes. For further information on utilizing the PURESPEED I/O buffer to support a variety of standards please see details of additional technical documentation at the end of this data sheet.

Differential Input Termination

The LatticeSC device allows two types of differential termination. The first is a single resistor across the differential inputs. The second is a center-tapped system where each input is terminated to the on-chip termination bus V_{CMT}. The V_{CMT} bus is DC-coupled through an internal capacitor to ground.

Figure 2-29 shows the differential termination schemes and Table 2-9 shows the nominal values of the termination resistors.

Figure 2-29. Differential Termination Scheme



Calibration

There are two calibration sources that are associated with the termination scheme used in the LatticeSC devices:

- DIFFR – This pin occurs in each bank that supports differential drivers and must be connected through a 1K+/-1% resistor to ground if differential outputs are used. Note that differential drivers are not supported in banks 1, 4 and 5.
- XRES – There is one of these pins per device. It is used for several functions including calibrating on-chip termination. This pin should always be connected through a 1K+/-1% resistor to ground.

The LatticeSC devices support two modes of calibration:

- Continuous – In this mode the SC devices continually calibrate the termination resistances. Calibration happens several times a second. Using this mode ensures that termination resistances remain calibrated as the silicon junction temperature changes.
- User Request – In this mode the calibration circuit operates continuously. However, the termination resistor values are only updated on the assertion of the calibration_update signal available to the core logic.

For more information on calibration, refer to the details of additional technical documentation at the end of this data sheet.

Hot Socketing

The LatticeSC devices have been carefully designed to ensure predictable behavior during power-up and power-down. To ensure proper power sequencing, care must be taken during power-up and power-down as described below. During power-up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits,

VDDAX25 needs to be connected independent of the use of the SERDES. This supply is used to control the SERDES CML I/O regardless of the SERDES being used in the design.

Supported Source Synchronous Interfaces

The LatticeSC devices contain a variety of hardware, such as delay elements, DDR registers and PLLs, to simplify the implementation of Source Synchronous interfaces. Table 2-11 lists Source Synchronous and DDR/QDR standards supported in the LatticeSC. For additional detail refer to technical information at the end of the data sheet.

Table 2-11. Source Synchronous Standards Table[1]

Source Synchronous Standard	Clocking	Speeds (MHz)	Data Rate (Mbps)
RapidIO	DDR	500	1000
SPI4.2 (POS-PHY4)/NPSI	DDR	500	1000
SFI4/XSBI	DDR SDR	334 667	667
XGMII	DDR	156.25	312
CSIX	SDR	250	250
QDRII/QDRII+ memory interface	DDR	300	600
DDR memory interface	DDR	240	480
DDRII memory interface	DDR	333	667
RLDRAM memory interface	DDR	400	800

1. Memory width is dependent on the system design and limited by the number of I/Os in the device.

flexiPCS™ (Physical Coding Sublayer Block)

flexiPCS Functionality

The LatticeSC family combines a high-performance FPGA fabric, high-performance I/Os and large embedded RAM in a single industry leading architecture. LatticeSC devices also feature up to 32 channels of embedded SERDES with associated Physical Coding Sublayer (PCS) logic. The flexiPCS logic can be configured to support numerous industry standard high-speed data transfer protocols.

Each channel of flexiPCS logic contains dedicated transmit and receive SERDES for high-speed, full-duplex serial data transfers at data rates up to 3.8 Gbps. The PCS logic in each channel can be configured to support an array of popular data protocols including SONET (STS-12/STS-12c, STS-48/STS-48c, and TFI-5 support of 10 Gbps or above), Gigabit Ethernet (compliant to the IEEE 1000BASE-X specification), 1.02 or 2.04 Gbps Fibre Channel, PCI-Express, and Serial RapidIO. In addition, the protocol based logic can be fully or partially bypassed in a number of configurations to allow users flexibility in designing their own high-speed data interface.

Protocols requiring data rates above 3.8 Gbps can be accommodated by dedicating either one pair or all four channels in one flexiPCS quad block to one data link. One quad can support full-duplex serial data transfers at data rates up to 15.2 Gbps. A single flexiPCS quad can be configured to support 10Gb Ethernet (with a fully compliant XAUI interface), 10Gb Fibre Channel, and x4 PCI-Express and 4x RapidIO.

The flexiPCS also provides bypass modes that allow a direct 8-bit or 10-bit interface from the SERDES to the FPGA logic which can also be geared to run at 1/2 speed for a 16-bit or 20-bit interface to the FPGA logic. Each SERDES pin can be DC coupled independently and can allow for both high-speed and low-speed operation down to DC rates on the same SERDES pin, as required by some Serial Digital Video applications.

The ispLEVER design tools from Lattice support all modes of the flexiPCS. Most modes are dedicated to applications associated with a specific industry standard data protocol. Other more general purpose modes allow a user to define their own operation. With ispLEVER, the user can define the mode for each quad in a design. Nine modes are currently supported by the ispLEVER design flow:

- 8-bit SERDES Only
- 10-bit SERDES Only
- SONET (STS-12/STS-48)
- Gigabit Ethernet
- Fibre Channel
- XAUI
- Serial RapidIO
- PCI-Express
- Generic 8b10b

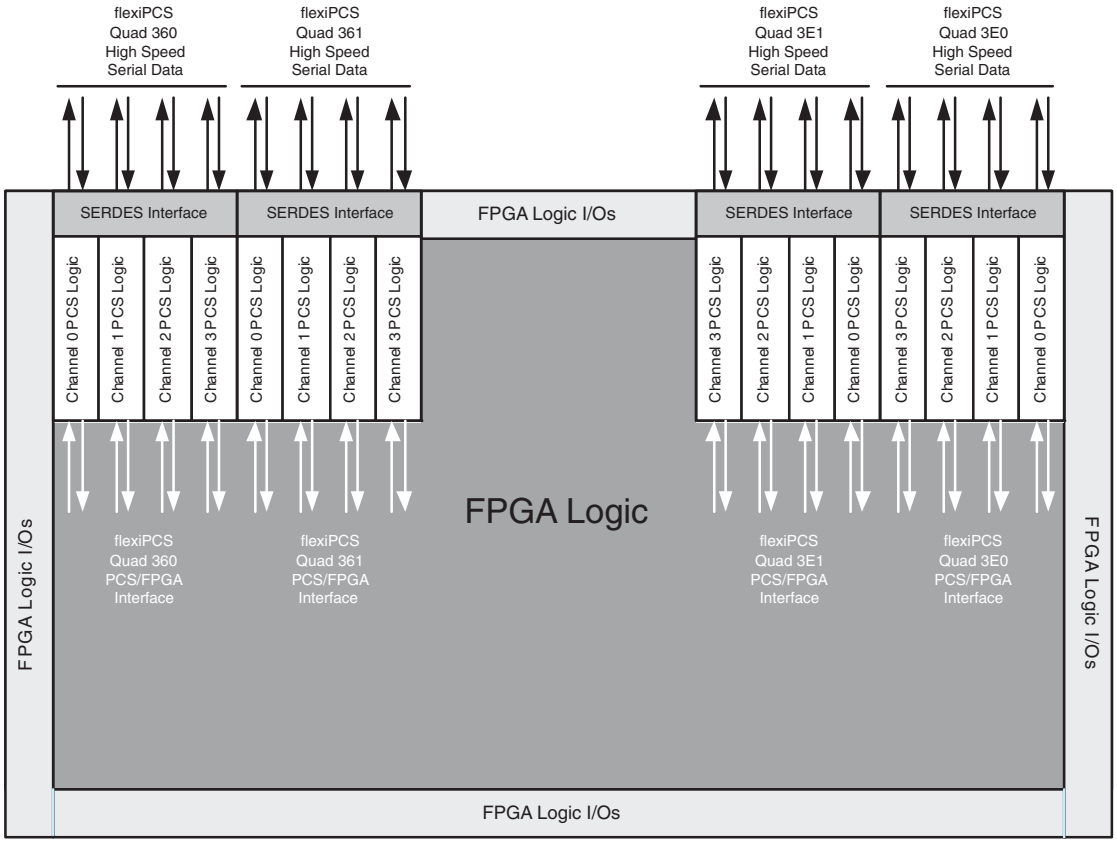
flexiPCS Quad

The flexiPCS logic is arranged in quads containing logic for four independent full-duplex data channels. Each device in the LatticeSC family has up to eight quads of flexiPCS logic. The LatticeSC Family Selection Guide table on the first page of this data sheet contains the number of flexiPCS channels present on the chip. Note that in some packages (particularly lower pin count packages), not all channels from all quads on a given device may be bonded to package pins.

Each quad supports up to four channels of full-duplex data and can be programmed into any one of several protocol based modes. Each quad requires its own reference clock which can be sourced externally or from the FPGA logic. The user can utilize between one and four channels in a quad, depending on the application.

Figure 2-30 shows an example of four flexiPCS quads in a LatticeSC device. Quads are labeled according to the address of their software controlled registers.

Figure 2-30. LatticeSC flexiPCS



Since each quad has its own reference clock, different quads can support different standards on the same chip. This feature makes the LatticeSC family of devices ideal for bridging between different standards.

Internal Logic Analyzer Capability (ispTRACY)

All LatticeSC devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time. For additional detail refer to technical information at the end of the data sheet.

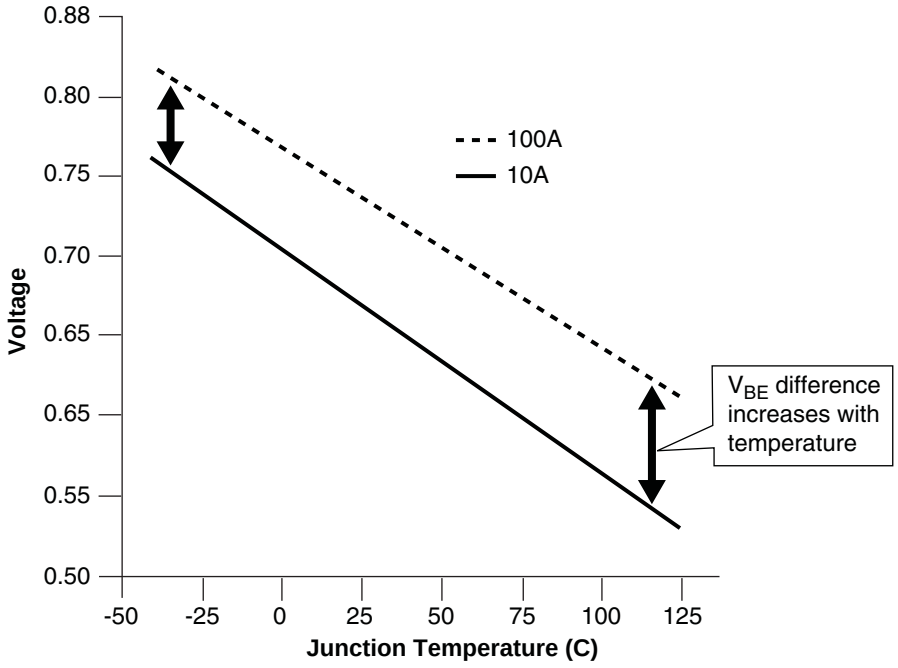
Temperature Sensing

Lattice provides a way to monitor the die temperature by using a temperature-sensing diode that is designed into every LatticeSC device. The difference in V_{BE} of the diode at two different forward currents varies with temperature. This relationship is shown in Figure 2-33. The accuracy of the temperature-sensing diode is typically +/- 10°C.

On packages that include PROBE_GND, the most accurate measurements will occur between the TEMP pin and the PROBE_GND pin. On packages that do not include PROBE_GND, measurements should be made between the TEMP pin and board ground.

This temperature-sensing diode is designed to work with an external temperature sensor such as the Maxim 1617A. The Maxim 1617A is configured to measure difference in V_{BE} (of the temperature-sensing diode) at 10µA and at 100µA. This difference in V_{BE} voltage varies with temperature at approximately 1.64 mV/°C. A typical device with a 85°C junction temperature will measure approximately 593mV. For additional detail refer to TN1115, Temperature Sensing Diode in LatticeSC Devices.

Figure 2-33. Sensing Diode Typical Characteristics



Oscillator

Every LatticeSC device has an internal CMOS oscillator, which is used as a master serial clock for configuration and is also available as a potential general purpose clock (MCK) for the FPGA core. There is a K divider (divide by 2/4/8/16/32/64/128) available with this oscillator to get lower MCK frequencies. This clock is available as a general purpose clock signal to the software routing tool. For additional detail refer to technical information at the end of the data sheet.

Density Shifting

The LatticeSC family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Switching Characteristics

All devices are 100% functionally tested. Listed below are representative values of internal and external timing parameters. For more specific, more precise, and worst-case guaranteed data at a particular temperature and voltage, use the values reported by the static timing analyzer in the ispLEVER design tool from Lattice and back-annotate to the simulation net list.

Figure 3-12. Waveforms First Read after Full Flag

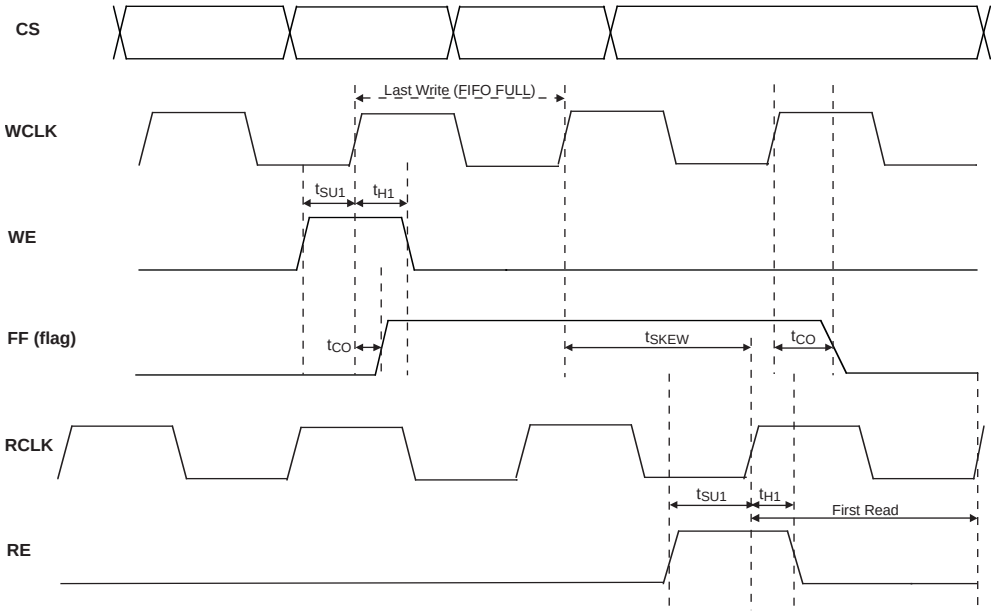
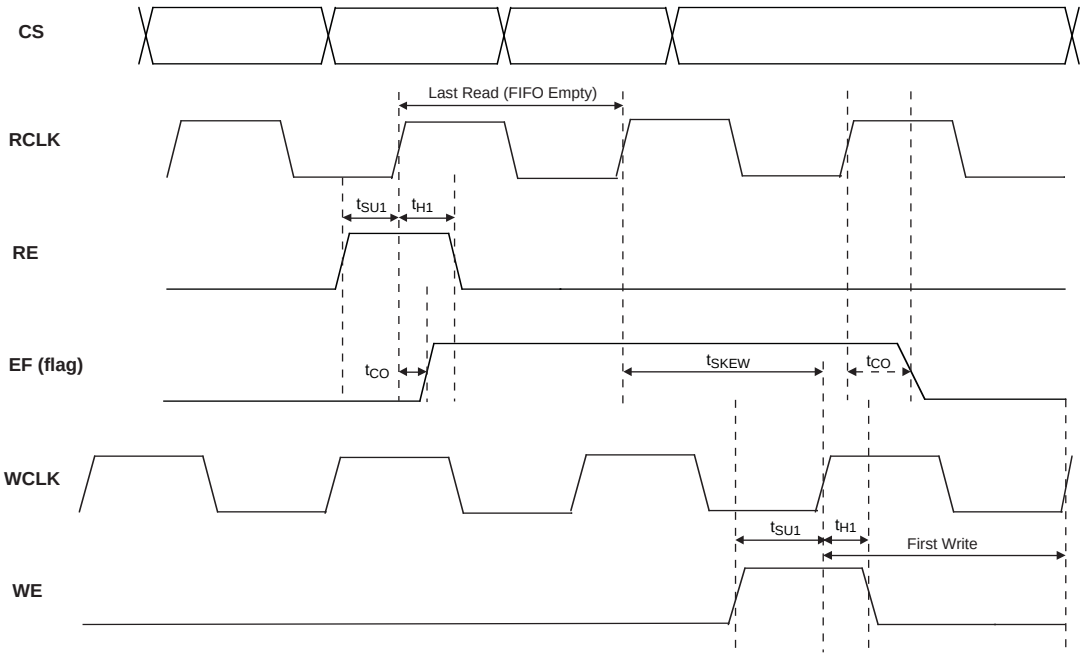


Figure 3-13. Waveform First Write after Empty Flag



LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2]

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C28	A_REFCLKP_L	-		A_REFCLKP_L	-	
D28	A_REFCLKN_L	-		A_REFCLKN_L	-	
B28	VCC12	-		VCC12	-	
F28	RESP_ULC	-		RESP_ULC	-	
J21	RESETN	1		RESETN	1	
J20	TSALLN	1		TSALLN	1	
K20	DONE	1		DONE	1	
K21	INITN	1		INITN	1	
K23	M0	1		M0	1	
J23	M1	1		M1	1	
J24	M2	1		M2	1	
K24	M3	1		M3	1	
K25	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
J25	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
K26	PL16C	7		PL16C	7	
K27	PL16D	7		PL16D	7	
D32	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
D31	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
M23	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
N23	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
E32	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
E31	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
J28	PL18C	7		PL18C	7	
K28	PL18D	7	VREF2_7	PL18D	7	VREF2_7
F32	PL20A	7		PL21A	7	
F31	PL20B	7		PL21B	7	
L25	PL20C	7		PL21C	7	
L26	PL20D	7		PL21D	7	
G31	PL21A	7		PL22A	7	
G32	PL21B	7		PL22B	7	
J29	PL22A	7		PL25A	7	
H29	PL22B	7		PL25B	7	
M25	PL22C	7		PL25C	7	
N25	PL22D	7		PL25D	7	
H31	PL25A	7		PL23A	7	
H32	PL25B	7		PL23B	7	
M24	PL25C	7	VREF1_7	PL23C	7	VREF1_7
N24	PL25D	7	DIFFR_7	PL23D	7	DIFFR_7
L32	PL26A	7	PCLKT7_1	PL35A	7	PCLKT7_1
M32	PL26B	7	PCLKC7_1	PL35B	7	PCLKC7_1
R25	PL26C	7	PCLKT7_3	PL35C	7	PCLKT7_3
R24	PL26D	7	PCLKC7_3	PL35D	7	PCLKC7_3
N31	PL27A	7	PCLKT7_0	PL36A	7	PCLKT7_0
N32	PL27B	7	PCLKC7_0	PL36B	7	PCLKC7_0
P27	PL27C	7	PCLKT7_2	PL36C	7	PCLKT7_2
P28	PL27D	7	PCLKC7_2	PL36D	7	PCLKC7_2
P30	PL29A	6	PCLKT6_0	PL38A	6	PCLKT6_0
P29	PL29B	6	PCLKC6_0	PL38B	6	PCLKC6_0
T23	PL29C	6	PCLKT6_1	PL38C	6	PCLKT6_1
T24	PL29D	6	PCLKC6_1	PL38D	6	PCLKC6_1

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB3	NC	-		PR58B	3	
AB4	NC	-		PR58A	3	
AG4	NC	-		PR57D	3	
AG3	NC	-		PR57C	3	
AA2	NC	-		PR57B	3	
AB2	NC	-		PR57A	3	
AA3	NC	-		PR56B	3	
AA4	NC	-		PR56A	3	
L5	NC	-		PR22D	2	
L6	NC	-		PR22C	2	
M2	NC	-		PR34B	2	
L2	NC	-		PR34A	2	
L3	NC	-		PR31B	2	
M3	NC	-		PR31A	2	
L4	NC	-		PR30B	2	
M4	NC	-		PR30A	2	
P7	NC	-		PR29D	2	
P8	NC	-		PR29C	2	
K1	NC	-		PR29B	2	
K2	NC	-		PR29A	2	
N6	NC	-		PR27D	2	
N7	NC	-		PR27C	2	
J2	NC	-		PR27B	2	
J1	NC	-		PR27A	2	
N5	NC	-		PR26D	2	
M5	NC	-		PR26C	2	
H3	NC	-		PR26B	2	
J3	NC	-		PR26A	2	
A5	VDDAX25_R	-		VDDAX25_R	-	
A28	VDDAX25_L	-		VDDAX25_L	-	
AJ25	NC	-		PB21A	5	
AK25	NC	-		PB21B	5	
AF20	NC	-		PB27C	5	
AG6	NC	-		PB62C	4	
AM7	NC	-		PB66A	4	
AL7	NC	-		PB66B	4	
AD13	NC	-		PB66C	4	
AC13	NC	-		PB66D	4	
AC20	NC	-		PB22C	5	
AD20	NC	-		PB22D	5	
AM9	NC	-		PB61A	4	
AM8	NC	-		PB61B	4	
AF13	NC	-		PB61C	4	
AE13	NC	-		PB61D	4	
E30	VCC12	-		VCC12	-	
E29	VCC12	-		VCC12	-	
E27	VCC12	-		VCC12	-	
E26	VCC12	-		VCC12	-	
E25	VCC12	-		VCC12	-	
E24	VCC12	-		VCC12	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
L1	PR31A	2		PR43A	2	
T10	PR30D	2		PR42D	2	
U10	PR30C	2		PR42C	2	
N2	PR30B	2		PR42B	2	
M2	PR30A	2		PR42A	2	
R11	PR29D	2		PR37D	2	
P11	PR29C	2		PR37C	2	
N4	PR29B	2		PR37B	2	
M4	PR29A	2		PR37A	2	
N5	PR27D	2		PR35D	2	
M5	PR27C	2		PR35C	2	
L2	PR27B	2		PR35B	2	
K2	PR27A	2		PR35A	2	
P8	PR26D	2		PR33D	2	
N8	PR26C	2		PR33C	2	
J2	PR26B	2		PR33B	2	
H2	PR26A	2		PR33A	2	
M6	PR25D	2		PR31D	2	
L6	PR25C	2		PR31C	2	
K3	PR25B	2		PR31B	2	
J3	PR25A	2		PR31A	2	
M8	PR23D	2	DIFFR_2	PR29D	2	DIFFR_2
L8	PR23C	2	VREF1_2	PR29C	2	VREF1_2
K4	PR23B	2		PR29B	2	
J4	PR23A	2		PR29A	2	
M7	PR22D	2		PR21D	2	
L7	PR22C	2		PR21C	2	
J5	PR22B	2		PR21B	2	
H5	PR22A	2		PR21A	2	
N9	PR21D	2		PR20D	2	
P9	PR21C	2		PR20C	2	
G3	PR21B	2		PR20B	2	
F3	PR21A	2		PR20A	2	
J6	PR18D	2	VREF2_2	PR18D	2	VREF2_2
H6	PR18C	2		PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
D2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
G4	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
F4	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
J7	PR16D	2		PR16D	2	
H7	PR16C	2		PR16C	2	
G5	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
F5	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
N27	PL47C	7	
P27	PL47D	7	
K33	PL49A	7	
L33	PL49B	7	
M30	PL49C	7	
N30	PL49D	7	
M31	PL51A	7	
N31	PL51B	7	
P24	PL51C	7	
R24	PL51D	7	
M33	PL56A	7	
N33	PL56B	7	
U25	PL56C	7	
T25	PL56D	7	
L34	PL57A	7	
M34	PL57B	7	
P29	PL57C	7	
R29	PL57D	7	
N34	PL60A	7	
P34	PL60B	7	
R27	PL60C	7	
T27	PL60D	7	
R32	PL61A	7	PCLKT7_1
R31	PL61B	7	PCLKC7_1
U24	PL61C	7	PCLKT7_3
T24	PL61D	7	PCLKC7_3
P33	PL62A	7	PCLKT7_0
R33	PL62B	7	PCLKC7_0
T26	PL62C	7	PCLKT7_2
U26	PL62D	7	PCLKC7_2
T32	PL64A	6	PCLKT6_0
T31	PL64B	6	PCLKC6_0
U29	PL64C	6	PCLKT6_1
V29	PL64D	6	PCLKC6_1
T30	PL65A	6	
U30	PL65B	6	
U27	PL65C	6	PCLKT6_3
V27	PL65D	6	PCLKC6_3
R34	PL66A	6	
T34	PL66B	6	
U28	PL66C	6	PCLKT6_2
V28	PL66D	6	PCLKC6_2
V30	PL69A	6	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AJ34	PL98A	6	
AK34	PL98B	6	
AB27	PL98C	6	
AC27	PL98D	6	
AF33	PL99A	6	
AG33	PL99B	6	
AC29	PL99C	6	
AD29	PL99D	6	
AE31	PL103A	6	
AF31	PL103B	6	
AF30	PL103C	6	
AF29	PL103D	6	
AH33	PL104A	6	
AJ33	PL104B	6	
AC28	PL104C	6	
AD28	PL104D	6	
AH32	PL107A	6	
AJ32	PL107B	6	
AD27	PL107C	6	
AE27	PL107D	6	VREF2_6
AG34	PL109A	6	
AH34	PL109B	6	
AC26	PL109C	6	
AB26	PL109D	6	
AK33	PL112A	6	
AL33	PL112B	6	
AG30	PL112C	6	
AH30	PL112D	6	
AL34	PL115A	6	
AM34	PL115B	6	
AJ30	PL115C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AK30	PL115D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AJ31	PL116A	6	
AH31	PL116B	6	
AD26	PL116C	6	
AD25	PL116D	6	
AL32	PL117A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AL31	PL117B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AG29	PL117C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AG28	PL117D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AF28	XRES	-	
AF27	TEMP	6	
AM33	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
V8	PR65D	3	PCLKC3_3
U8	PR65C	3	PCLKT3_3
U5	PR65B	3	
T5	PR65A	3	
V6	PR64D	3	PCLKC3_1
U6	PR64C	3	PCLKT3_1
T4	PR64B	3	PCLKC3_0
T3	PR64A	3	PCLKT3_0
U9	PR62D	2	PCLKC2_2
T9	PR62C	2	PCLKT2_2
R2	PR62B	2	PCLKC2_0
P2	PR62A	2	PCLKT2_0
T11	PR61D	2	PCLKC2_3
U11	PR61C	2	PCLKT2_3
R4	PR61B	2	PCLKC2_1
R3	PR61A	2	PCLKT2_1
T8	PR60D	2	
R8	PR60C	2	
P1	PR60B	2	
N1	PR60A	2	
R6	PR57D	2	
P6	PR57C	2	
M1	PR57B	2	
L1	PR57A	2	
T10	PR56D	2	
U10	PR56C	2	
N2	PR56B	2	
M2	PR56A	2	
R11	PR51D	2	
P11	PR51C	2	
N4	PR51B	2	
M4	PR51A	2	
N5	PR49D	2	
M5	PR49C	2	
L2	PR49B	2	
K2	PR49A	2	
P8	PR47D	2	
N8	PR47C	2	
J2	PR47B	2	
H2	PR47A	2	
M6	PR45D	2	
L6	PR45C	2	
K3	PR45B	2	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
J1	PR25B	2		PR38B	2	
K1	PR25A	2		PR38A	2	
V12	PR24D	2		PR34D	2	
U12	PR24C	2		PR34C	2	
K2	PR24B	2		PR34B	2	
J2	PR24A	2		PR34A	2	
R10	PR22D	2		PR30D	2	
T10	PR22C	2		PR30C	2	
L5	PR22B	2		PR30B	2	
K5	PR22A	2		PR30A	2	
P9	PR21D	2		PR26D	2	
N9	PR21C	2		PR26C	2	
L6	PR21B	2		PR26B	2	
K6	PR21A	2		PR26A	2	
M8	PR20D	2		PR19D	2	
M9	PR20C	2		PR19C	2	
H1	PR20B	2		PR19B	2	
G1	PR20A	2		PR19A	2	
U14	PR18D	2	VREF2_2	PR18D	2	VREF2_2
T14	PR18C	2		PR18C	2	
H2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
G2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
H3	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
G3	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
R11	PR16D	2		PR15D	2	
P11	PR16C	2		PR15C	2	
J5	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
J6	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
P18	VCCJ	-		VCCJ	-	
P19	TDO	-	TDO	TDO	-	TDO
R21	TMS	-		TMS	-	
P20	TCK	-		TCK	-	
P12	TDI	-		TDI	-	
P17	PROGRAMN	1		PROGRAMN	1	
P21	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
P13	CCLK	1		CCLK	1	
H10	RESP_URC	-		RESP_URC	-	
N13	VCC12	-		VCC12	-	
H9	A_REFCLKN_R	-		A_REFCLKN_R	-	
G9	A_REFCLKP_R	-		A_REFCLKP_R	-	
F2	VCC12	-		VCC12	-	
H4	A_VDDIB0_R	-		A_VDDIB0_R	-	
C1	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D1	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
F1	VCC12	-		VCC12	-	
A3	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
E1	A_VDDOB0_R	-		A_VDDOB0_R	-	
B3	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
C2	A_VDDOB1_R	-		A_VDDOB1_R	-	
A4	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
B2	VCC12	-		VCC12	-	
B4	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
E3	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
D3	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
M10	VCC12	-		VCC12	-	
E2	A_VDDIB1_R	-		A_VDDIB1_R	-	
J11	VCC12	-		VCC12	-	
M11	A_VDDIB2_R	-		A_VDDIB2_R	-	
D4	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
E4	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
K9	VCC12	-		VCC12	-	
A5	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
D2	A_VDDOB2_R	-		A_VDDOB2_R	-	
B5	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
L10	A_VDDOB3_R	-		A_VDDOB3_R	-	
B6	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
G6	VCC12	-		VCC12	-	
A6	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
E5	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
D5	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
K12	VCC12	-		VCC12	-	
L13	A_VDDIB3_R	-		A_VDDIB3_R	-	
N14	VCC12	-		VCC12	-	
F9	B_VDDIB0_R	-		B_VDDIB0_R	-	
D6	B_HDINP0_R	-	PCS 3E1 CH 0 IN P	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
E6	B_HDINN0_R	-	PCS 3E1 CH 0 IN N	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
J8	VCC12	-		VCC12	-	
B7	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
G4	B_VDDOB0_R	-		B_VDDOB0_R	-	
A7	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
K8	B_VDDOB1_R	-		B_VDDOB1_R	-	
A8	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L9	VCC12	-		VCC12	-	
B8	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
E7	B_HDINN1_R	-	PCS 3E1 CH 1 IN N	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
D7	B_HDINP1_R	-	PCS 3E1 CH 1 IN P	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
F10	VCC12	-		VCC12	-	
K13	B_VDDIB1_R	-		B_VDDIB1_R	-	

Conventional Packaging

Commercial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-7F256C	-7	fpBGA	256	COM	15.2
LFSC3GA15E-6F256C	-6	fpBGA	256	COM	15.2
LFSC3GA15E-5F256C	-5	fpBGA	256	COM	15.2
LFSC3GA15E-7F900C	-7	fpBGA	900	COM	15.2
LFSC3GA15E-6F900C	-6	fpBGA	900	COM	15.2
LFSC3GA15E-5F900C	-5	fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-7F256C	-7	fpBGA	256	COM	15.2
LFSCM3GA15EP1-6F256C	-6	fpBGA	256	COM	15.2
LFSCM3GA15EP1-5F256C	-5	fpBGA	256	COM	15.2
LFSCM3GA15EP1-7F900C	-7	fpBGA	900	COM	15.2
LFSCM3GA15EP1-6F900C	-6	fpBGA	900	COM	15.2
LFSCM3GA15EP1-5F900C	-5	fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-7F900C	-7	fpBGA	900	COM	25.4
LFSC3GA25E-6F900C	-6	fpBGA	900	COM	25.4
LFSC3GA25E-5F900C	-5	fpBGA	900	COM	25.4
LFSC3GA25E-7FF1020C[1]	-7	Organic fcBGA	1020	COM	25.4
LFSC3GA25E-6FF1020C[1]	-6	Organic fcBGA	1020	COM	25.4
LFSC3GA25E-5FF1020C[1]	-5	Organic fcBGA	1020	COM	25.4
LFSC3GA25E-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-7F900C	-7	fpBGA	900	COM	25.4
LFSCM3GA25EP1-6F900C	-6	fpBGA	900	COM	25.4
LFSCM3GA25EP1-5F900C	-5	fpBGA	900	COM	25.4
LFSCM3GA25EP1-7FF1020C[1]	-7	Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-6FF1020C[1]	-6	Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-5FF1020C[1]	-5	Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-7FC1152C[1]	-7	Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-7FF1152C	-7	Organic fcBGA	1152	COM	80.1
LFSC3GA80E-6FF1152C	-6	Organic fcBGA	1152	COM	80.1
LFSC3GA80E-5FF1152C	-5	Organic fcBGA	1152	COM	80.1
LFSC3GA80E-7FC1704C[1]	-7	Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-7FF1704C	-7	Organic fcBGA	1704	COM	80.1
LFSC3GA80E-6FF1704C	-6	Organic fcBGA	1704	COM	80.1
LFSC3GA80E-5FF1704C	-5	Organic fcBGA	1704	COM	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-7FC1152C[1]	-7	Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-7FF1152C	-7	Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-6FF1152C	-6	Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-5FF1152C	-5	Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-7FC1704C[1]	-7	Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-7FF1704C	-7	Organic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-6FF1704C	-6	Organic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-5FF1704C	-5	Organic fcBGA	1704	COM	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA115E-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	115.2
LFSC3GA115E-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	115.2
LFSC3GA115E-6FF1152C	-6	Organic fcBGA	1152	COM	115.2
LFSC3GA115E-5FF1152C	-5	Organic fcBGA	1152	COM	115.2
LFSC3GA115E-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	115.2
LFSC3GA115E-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	115.2
LFSC3GA115E-6FF1704C	-6	Organic fcBGA	1704	COM	115.2
LFSC3GA115E-5FF1704C	-5	Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Industrial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-6FN256I	-6	Lead-Free fpBGA	256	IND	15.2
LFSC3GA15E-5FN256I	-5	Lead-Free fpBGA	256	IND	15.2
LFSC3GA15E-6FN900I	-6	Lead-Free fpBGA	900	IND	15.2
LFSC3GA15E-5FN900I	-5	Lead-Free fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-6FN256I	-6	Lead-Free fpBGA	256	IND	15.2
LFSCM3GA15EP1-5FN256I	-5	Lead-Free fpBGA	256	IND	15.2
LFSCM3GA15EP1-6FN900I	-6	Lead-Free fpBGA	900	IND	15.2
LFSCM3GA15EP1-5FN900I	-5	Lead-Free fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-6FN900I	-6	Lead-Free fpBGA	900	IND	25.4
LFSC3GA25E-5FN900I	-5	Lead-Free fpBGA	900	IND	25.4
LFSC3GA25E-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	25.4
LFSC3GA25E-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	25.4
LFSC3GA25E-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	25.4
LFSC3GA25E-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-6FN900I	-6	Lead-Free fpBGA	900	IND	25.4
LFSCM3GA25EP1-5FN900I	-5	Lead-Free fpBGA	900	IND	25.4
LFSCM3GA25EP1-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	25.4
LFSCM3GA25EP1-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	40.4
LFSC3GA40E-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	40.4
LFSC3GA40E-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-6FCN1152I[2]	-6	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-5FCN1152I[2]	-5	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	40.4
LFSC3GA40E-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.